

表面处理-高性能选择性化学镍金技术

Final Finishing – High Performance Selective ENIG Technology

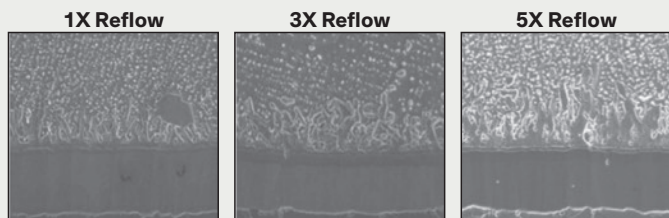


DURAPOSIT™ SMT 820 化学镍
AUROLECTROLESS™ SMT 520 化学浸金

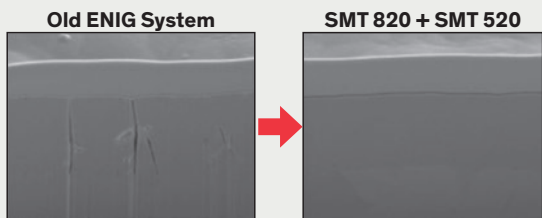
Advantages 优点

- High Ni corrosion resistance without spike observed after 3 times of OSP pass
抗镍腐蚀能力高可以通过三次OSP后处理而几乎无“镍黑牙”
- Capable to pass SO₂ gas corrosion test
能通过SO₂腐蚀测试
- Above 2μ” gold thickness is achievable at low gold content (0.8 g/L)
低金浓度操作下(0.8 g/L)金层可超过2微英寸金层厚度
- Dense gold deposits at high Ni/Cu ion contamination bath condition to ensure good solderability
高镍铜污染时仍可维持高密度金层而保持良好的可焊性
- Excellent solderability for Tin-Lead and Lead free solder joint
对于锡铅与无铅焊料具有优异的焊锡性
- No significant performance effect under dry film leaching condition
对干膜有机物析出不敏感，专用于选择性化镍金制程

多次回流焊的IMC没有太大的高低变化，具有优异的可焊性



FIB切片明显可见三次OSP后没有镍腐蚀



经过三次OSP后盲孔上方镍腐蚀大幅改善SEM图

